SHARP GP2W0112YP

 $(T_a=25^{\circ}C)$

GP2W0112YP

■ Features

- 1. Compliant with IrDA1.2 low power
- 2. Integrated package of transmitter/receiver. (7.9×2.85×height 2.15mm)
- 3. Low voltage operation (V_{CC}: 1.7 to 2.5V)
- 4. Low dissipation current due to shut-down function (Dissipation current at shut-down mode:Max. $0.1\mu A$)
- 5. Soldering reflow type
- 6. Shield type

■ Applications

- 1. Cellular phones, PHS
- 2. Personal information tools

■ Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Supply voltage	V_{CC}	0 to 5.0	V
LED Supply voltage	V_{LEDA}	0 to 6.0	V
*1 Peak forward current	I_{FM}	60	mA
Operating temperature	T_{opr}	-40 to +85	°C
Storage temperature	T_{stg}	-40 to +85	°C
*2 Soldering temperature	T _{sol}	260	°C

^{*1} Pulse width 78.1µs, Duty ratio:3/16

■ Recommended Operating Conditions

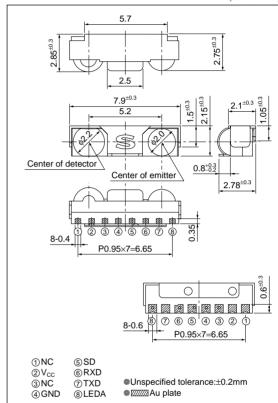
Parameter	Symbol	Rating	Unit
Supply voltage	V_{CC}	1.7 to 2.5	V
Transmission rate	BR	2.4 to 115.2	kb/s
High level input voltage (SD terminal)	V_{IHSD}	$V_{CC} \times 0.8$ to V_{CC}	V
Low level input voltage (SD terminal)	V_{ILSD}	0 to V _{CC} ×0.2	V
*3 High level input voltage (TXD)	V_{IHTXD}	$V_{CC} \times 0.8$ to V_{CC}	V
*3 Low level input voltage (TXD)	V _{ILTXD}	0 to V _{CC} ×0.2	V

^{*3} Refer to Fig.8

IrDA Transceiver Module Compliant with IrDA1.2 Low Power

■ Outline Dimensions

(Unit: mm)



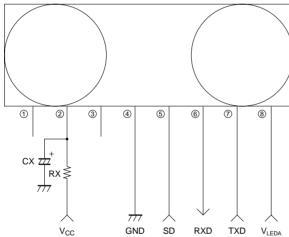
^{*2} For MAX. 10s

Flectro-	ontical	Charac	teristics
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■ Electro-optical Characteristics						$_{a}$ =25°C, V_{CC} =1.7 to 2.5V)	
	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
	Dissipation current at no input signal	I _{CC}	V_{CC} =1.8V, No input light, output terminal open, V_{ILSD} =0V	_	90	120	μА
e	S/D dissipation current	I _{CC-S}	V_{CC} =1.8V, output terminal open No input light, V_{IHSD} = V_{CC}	_	0.01	0.1	μΑ
side	High level output voltage	V _{OH}	$I_{OH}=200\mu A^{*4}$	V _{CC} -0.4	-	-	V
Receiver	Low level output voltage	V _{OL}	I _{OL} =200μA*4	-	-	0.4	V
ece	Low level pules width	$t_{\rm w}$	BR=115.2kb/s, ¢≤15°*4	1.28	_	6.0	μs
R	Rise time	t _r	BR=115.2kb/s, $C_L=10pF^{*4}$	_	_	50	ns
	Fall time	t _f	BR=115.2kb/s, C _L =10pF*4	_	_	50	ns
	Maximum communication distance	L	BR=115.2kb/s, φ≤15°*4	21	_	_	cm
Transmitter side	Radiant intensity	I_{E}	BR=115.2kb/s, $\phi \le 15^{\circ}$, $V_{CC}=1.8V^{*5}$	4.0	_	25	mW/sr
Trans	Peak emission wavelength	λ_{p}	$(V_{LEDA}=3.6V, V_{IHTXD}=1.5V)$	850	870	900	nm

^{*4} Refer to Fig.4, 5, 6

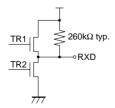
Fig.1 Recommended External Circuit



*I/O	Truth	table
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SD	TXD	LED	Receiver	TR1	TR2	RXD
	High	ON	Don't care	-	-	Not valid
Low	Low	OFF	IrDA signal	OFF	ON	Low
	LOW		No signal	ON	OFF	High
High	Don't care OFF		Don't care	OFF	OFF	Pull-up

*RXD Eruivalent circuit



(1)	NC
(2)	V_{CC}

- ③ NC 4 GND
- ⑤ SD
- ® RXD
- 7 TXD
- 8 LEDA

Components	Recommended values
CY	1uE/6 3\/ (Note)

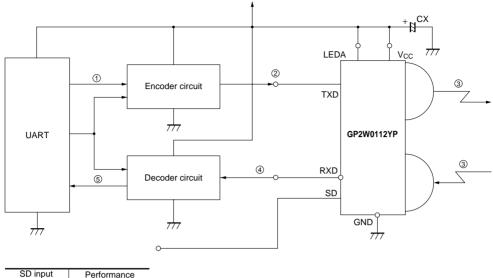
(Note) Please choose the most suttable CX according to the noise level and noise frequency of power supply.

Depend on noise level and noise frequency of power supply. CX does not work well. there are cases that some pulse noises from RXD other than signal will occur in certain communication area. Please check by fihish product that there are no problem at all communication area and all

If there are any problem, please check by inserting RX (1 to 10Ω) in the circuit drawing. Pin 1 and Pin 3, are not connected internally.

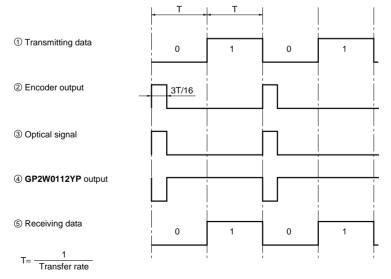
^{*5} Refer to Fig.7, 8, 9

Fig.2 System Configuration



SD input	Performance
Low	Normal mode
High	Shut down mode

Fig.3 Example of Signal Waveform



Transfer rate; 2.4kb/s,9.6kb/s,19.2kb/s,38.4kb/s,57.6kb/s,115.2kb/s

Fig.4 Input Signal Waveforrm (Receiver side)

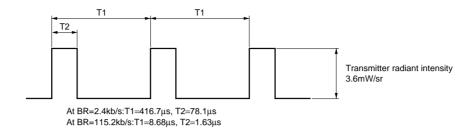


Fig.5 Output Waveform Specification (Receiver side)

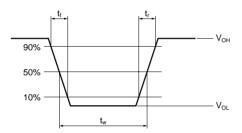
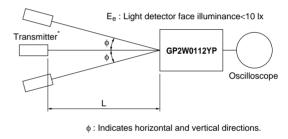


Fig.6 Standard Optical System (Receiver side)



*Transmitter shall use **GP2W0112YP** (λp=870nm TYP.) which is adjusted the radiation intensity at 3.6mW/sr

Fig.7 Output Waveform Specification (Transmitter side)

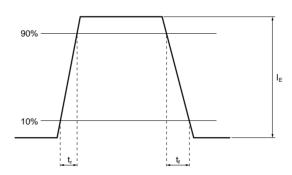


Fig.8 Standard Optical System (Transmitter side)

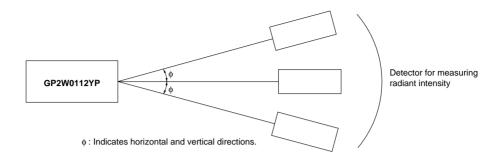


Fig.9 Recommended Circuit of Transmitter side

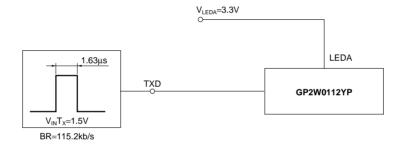
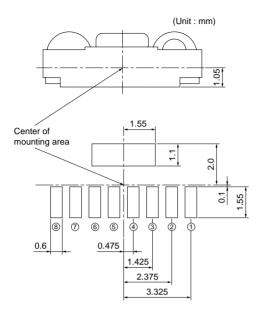


Fig.10 Recommended PCB Foot Pattern

Dimensions are shown for reference

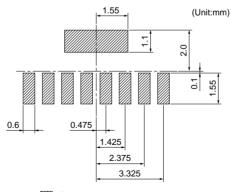


Terminal	Symbol
NC (Connectable to GND)	NC
V _{CC}	V _{cc}
NC (Connectable to V _{CC})	NC
Ground	GND
Shutdown	SD
Receiver data output	RXD
Transmitter data input	TXD
LED anode	LEDA
	V _{CC} NC (Connectable to V _{CC}) Ground Shutdown Receiver data output Transmitter data input

Connect foot pattern of shield case to GND pattern

Fig.11 Recommended Size of Solder Creamed Paste (Reference)

Please open the solder mask as below so that the size of solder creamed paste for this device before reflow soldering must be as large as one of the foot pattern land indicated Fig.10



Solder paste area

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